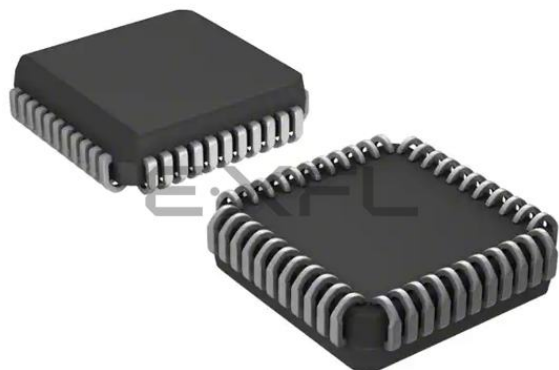




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

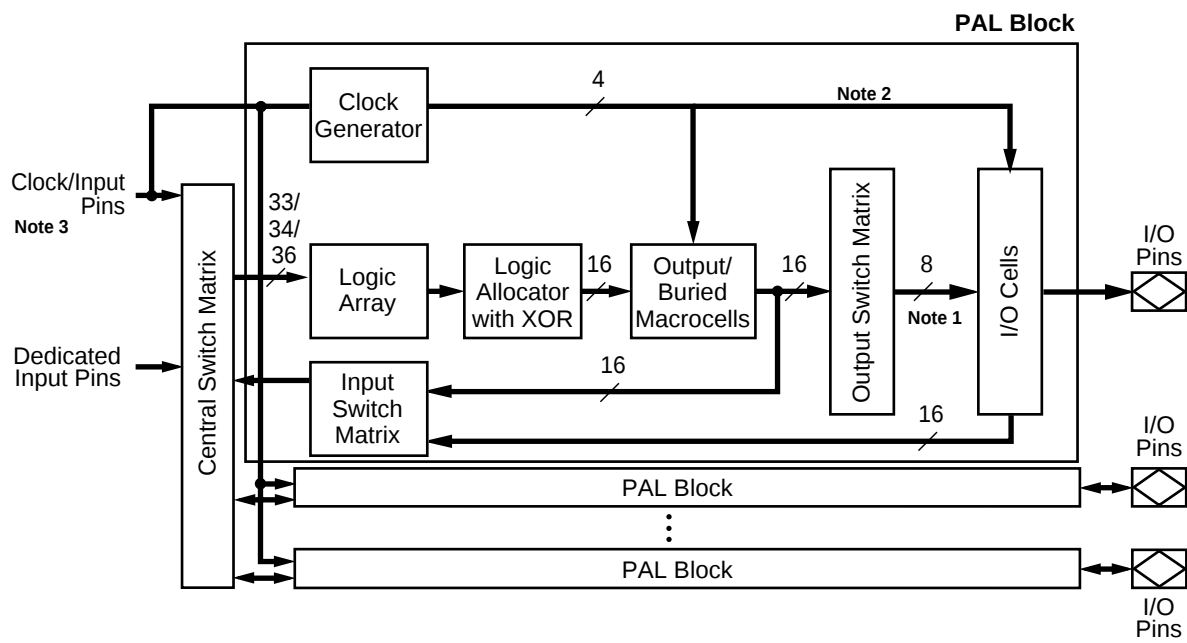
Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	32
Number of Gates	-
Number of I/O	32
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-32-32-10jnc

FUNCTIONAL DESCRIPTION

The fundamental architecture of ispMACH 4A devices (Figure 1) consists of multiple, optimized PAL[®] blocks interconnected by a central switch matrix. The central switch matrix allows communication between PAL blocks and routes inputs to the PAL blocks. Together, the PAL blocks and central switch matrix allow the logic designer to create large designs in a single device instead of having to use multiple devices.

The key to being able to make effective use of these devices lies in the interconnect schemes. In the ispMACH 4A architecture, the macrocells are flexibly coupled to the product terms through the logic allocator, and the I/O pins are flexibly coupled to the macrocells due to the output switch matrix. In addition, more input routing options are provided by the input switch matrix. These resources provide the flexibility needed to fit designs efficiently.



17466G-001

Figure 1. ispMACH 4A Block Diagram and PAL Block Structure

Notes:

1. 16 for ispMACH 4A devices with 1:1 macrocell-I/O cell ratio (see next page).
2. Block clocks do not go to I/O cells in M4A(3,5)-32/32.
3. M4A(3,5)-192, M4A(3,5)-256, M4A3-384, and M4A3-512 have dedicated clock pins which cannot be used as inputs and do not connect to the central switch matrix.

Table 4. Architectural Summary of ispMACH 4A devices

	ispMACH 4A Devices	
	M4A3-64/32, M4A5-64/32 M4A3-96/48, M4A5-96/48 M4A3-128/64, M4A5-128/64 M4A3-192/96, M4A5-192/96 M4A3-256/128, M4A5-256/128 M4A3-384 M4A3-512	M4A3-32/32 M4A5-32/32 M4A3-64/64 M4A3-256/160 M4A3-256/192
Macrocell-I/O Cell Ratio	2:1	1:1
Input Switch Matrix	Yes	Yes ¹
Input Registers	Yes	No
Central Switch Matrix	Yes	Yes
Output Switch Matrix	Yes	Yes

The Macrocell-I/O cell ratio is defined as the number of macrocells versus the number of I/O cells internally in a PAL block (Table 4).

The central switch matrix takes all dedicated inputs and signals from the input switch matrices and routes them as needed to the PAL blocks. Feedback signals that return to the same PAL block still must go through the central switch matrix. This mechanism ensures that PAL blocks in ispMACH 4A devices communicate with each other with consistent, predictable delays.

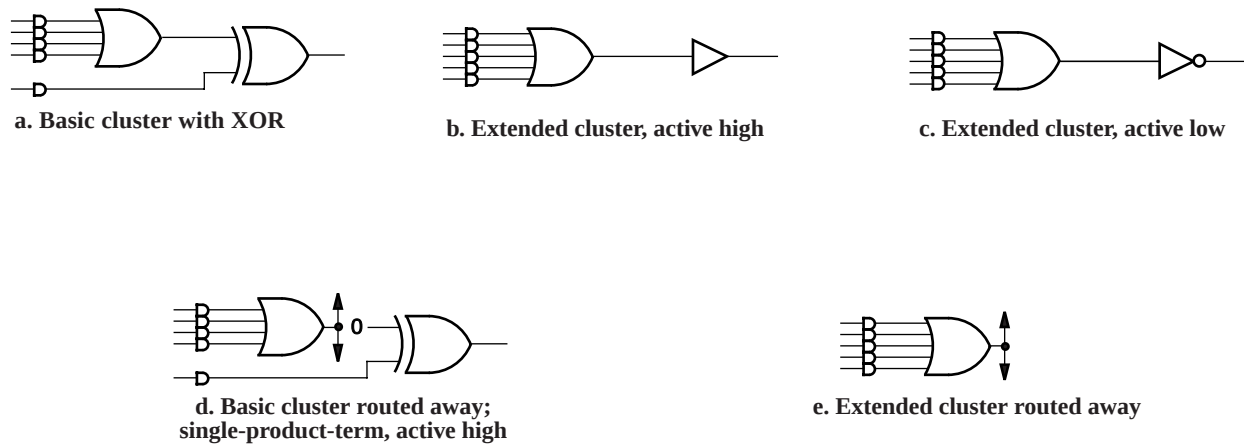
The central switch matrix makes a ispMACH 4A device more advanced than simply several PAL devices on a single chip. It allows the designer to think of the device not as a collection of blocks, but as a single programmable device; the software partitions the design into PAL blocks through the central switch matrix so that the designer does not have to be concerned with the internal architecture of the device.

Each PAL block consists of:

- ◆ Product-term array
- ◆ Logic allocator
- ◆ Macrocells
- ◆ Output switch matrix
- ◆ I/O cells
- ◆ Input switch matrix
- ◆ Clock generator

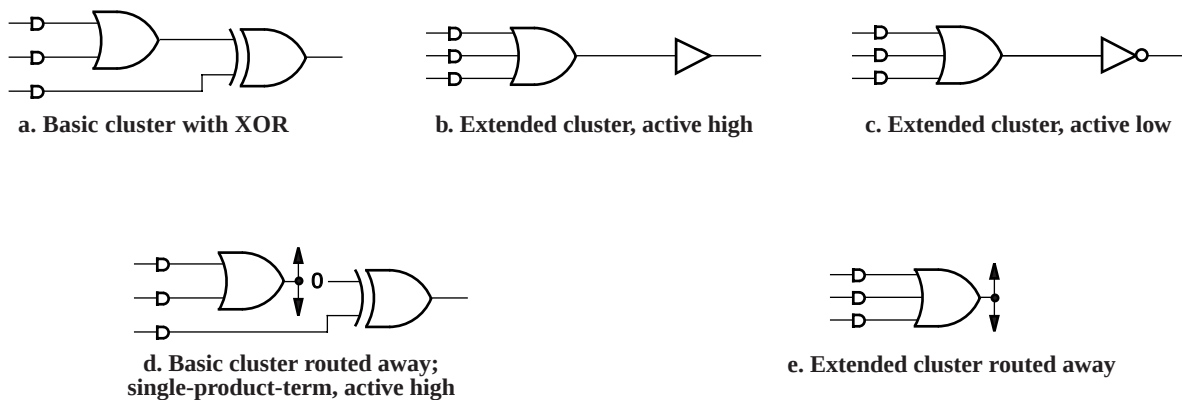
Notes:

1. M4A3-64/64 internal switch matrix functionality embedded in central switch matrix.



17466G-007

Figure 3. Logic Allocator Configurations: Synchronous Mode



17466G-008

Figure 4. Logic Allocator Configurations: Asynchronous Mode

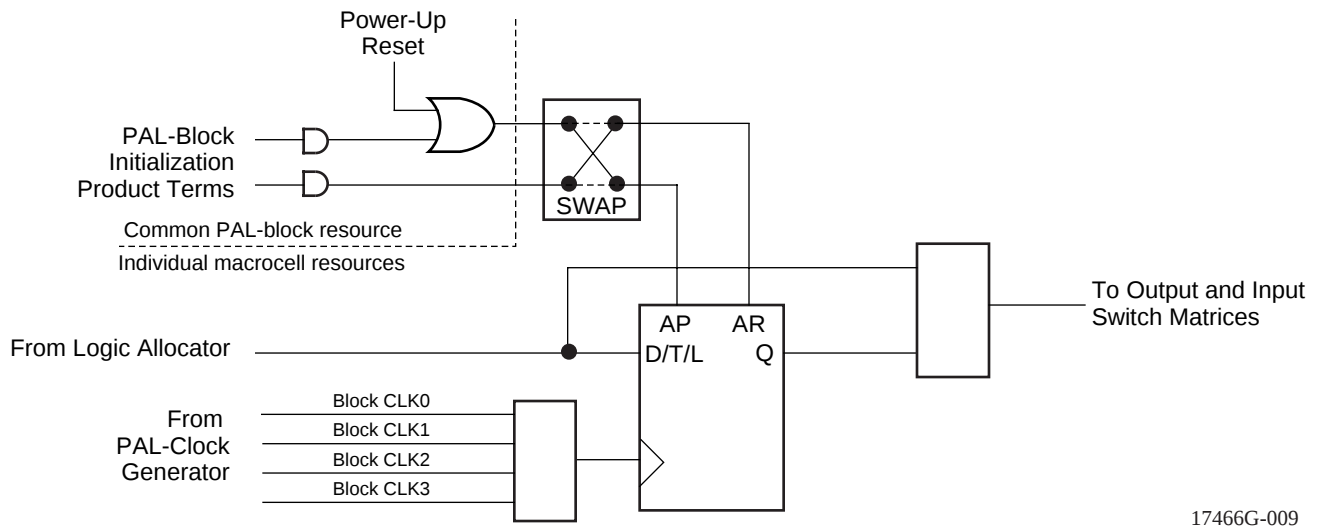
Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

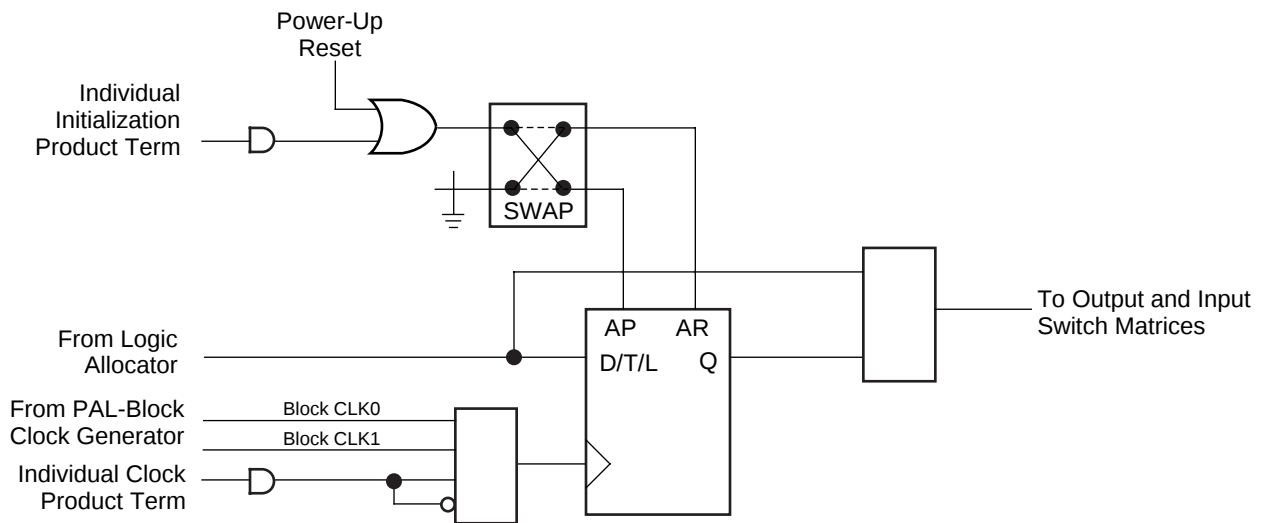
Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode

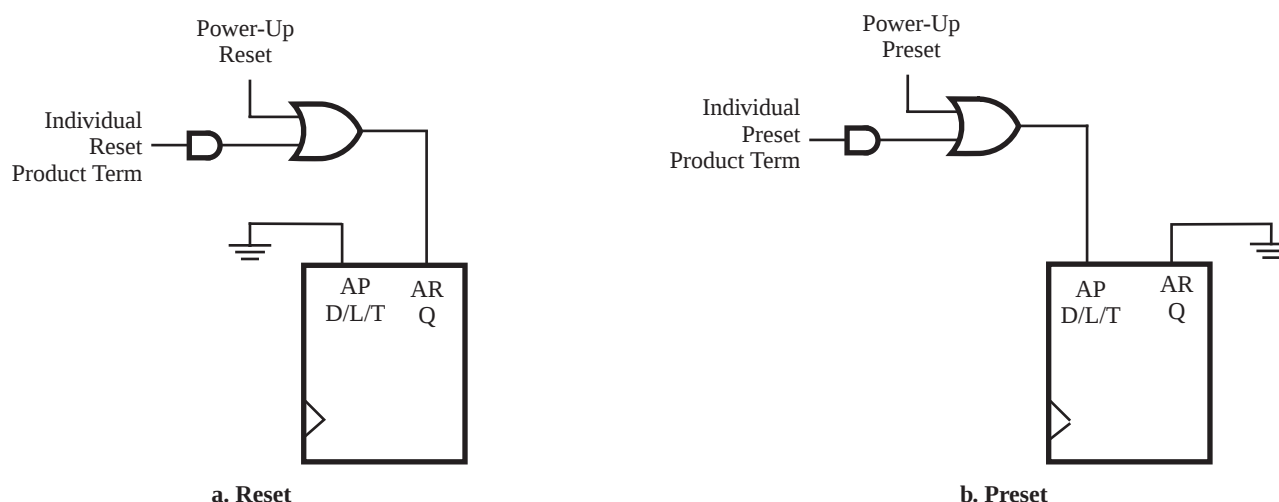


b. Asynchronous mode

Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



17466G-014

17466G-015

Figure 8. Asynchronous Mode Initialization Configurations

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

AR	AP	CLK/LE ¹	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:

1. Transparent latch is unaffected by AR, AP

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M12, M13	I/O3, I/O4, I/O5, I/O6
M14, M15	I/O4, I/O5, I/O6, I/O7

I/O Cell	Available Macrocells
I/O0	M0, M1, M2, M3, M4, M5, M6, M7
I/O1	M2, M3, M4, M5, M6, M7, M8, M9
I/O2	M4, M5, M6, M7, M8, M9, M10, M11
I/O3	M6, M7, M8, M9, M10, M11, M12, M13
I/O4	M8, M9, M10, M11, M12, M13, M14, M15
I/O5	M0, M1, M10, M11, M12, M13, M14, M15
I/O6	M0, M1, M2, M3, M12, M13, M14, M15
I/O7	M0, M1, M2, M3, M4, M5, M14, M15

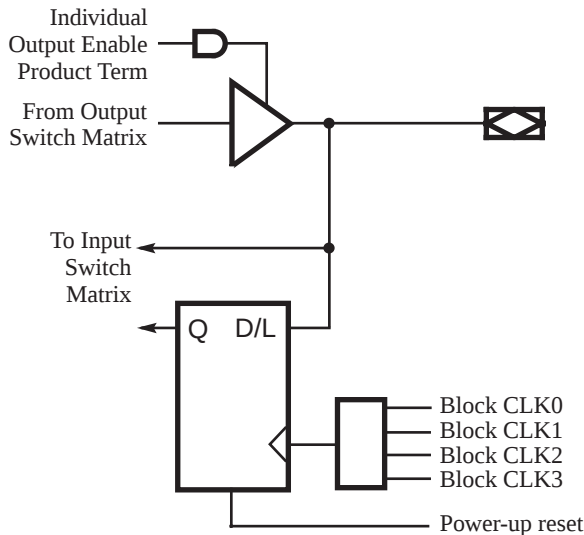
Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
M0	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M1	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M2	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M3	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M4	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M5	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M6	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M7	I/O0	I/O1	I/O2	I/O3	I/O4	I/O5	I/O6	I/O7
M8	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M9	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M10	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M11	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M12	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M13	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M14	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15
M15	I/O8	I/O9	I/O10	I/O11	I/O12	I/O13	I/O14	I/O15

I/O Cell	Available Macrocells							
I/O0	M0	M1	M2	M3	M4	M5	M6	M7
I/O1	M0	M1	M2	M3	M4	M5	M6	M7
I/O2	M0	M1	M2	M3	M4	M5	M6	M7
I/O3	M0	M1	M2	M3	M4	M5	M6	M7
I/O4	M0	M1	M2	M3	M4	M5	M6	M7
I/O5	M0	M1	M2	M3	M4	M5	M6	M7
I/O6	M0	M1	M2	M3	M4	M5	M6	M7
I/O7	M0	M1	M2	M3	M4	M5	M6	M7

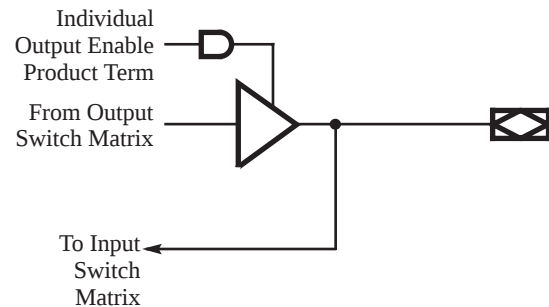
I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.



17466G-017

Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio



17466G-018

Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as “time-domain-multiplexed” data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary ScanTest Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level “1.” For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

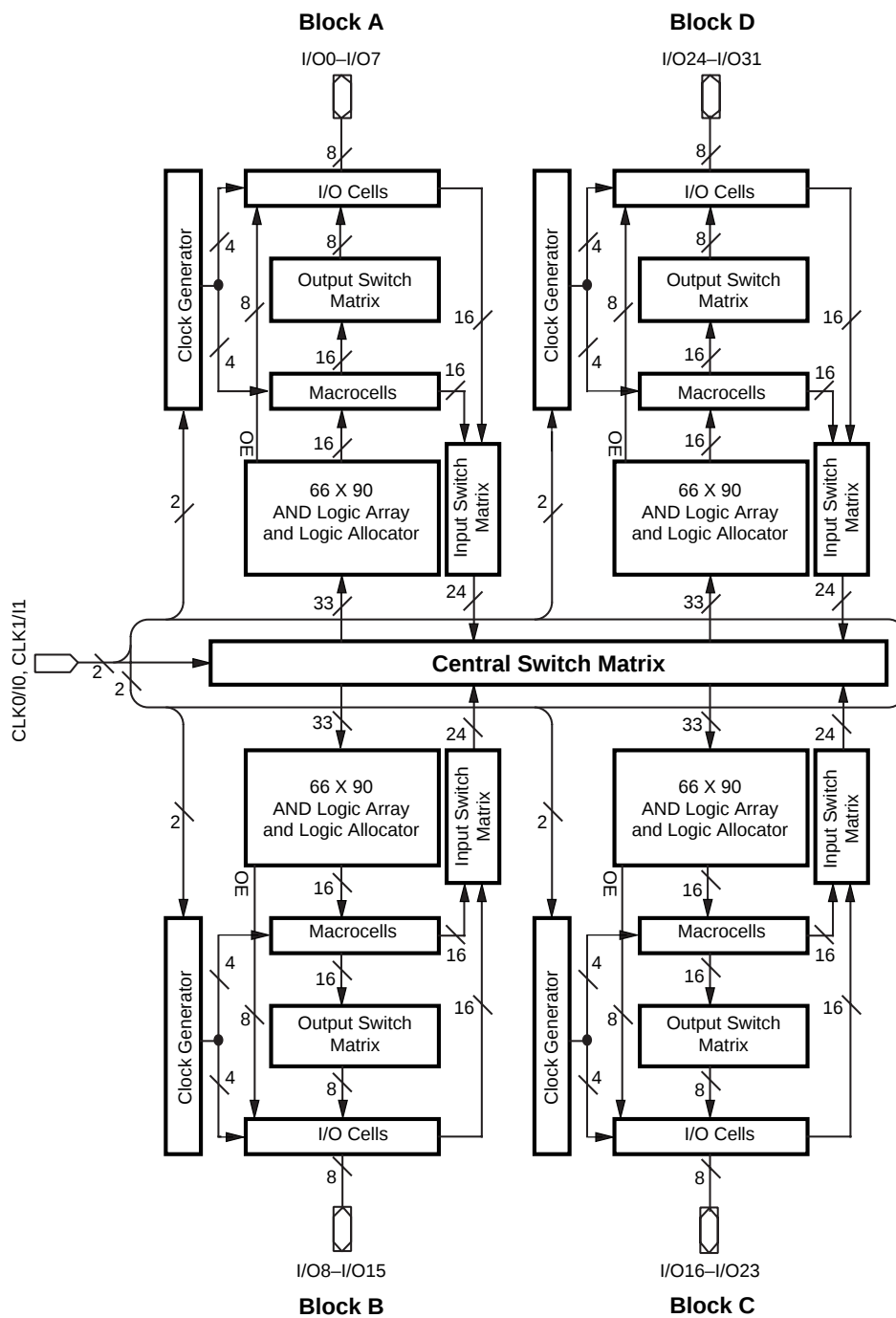
SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

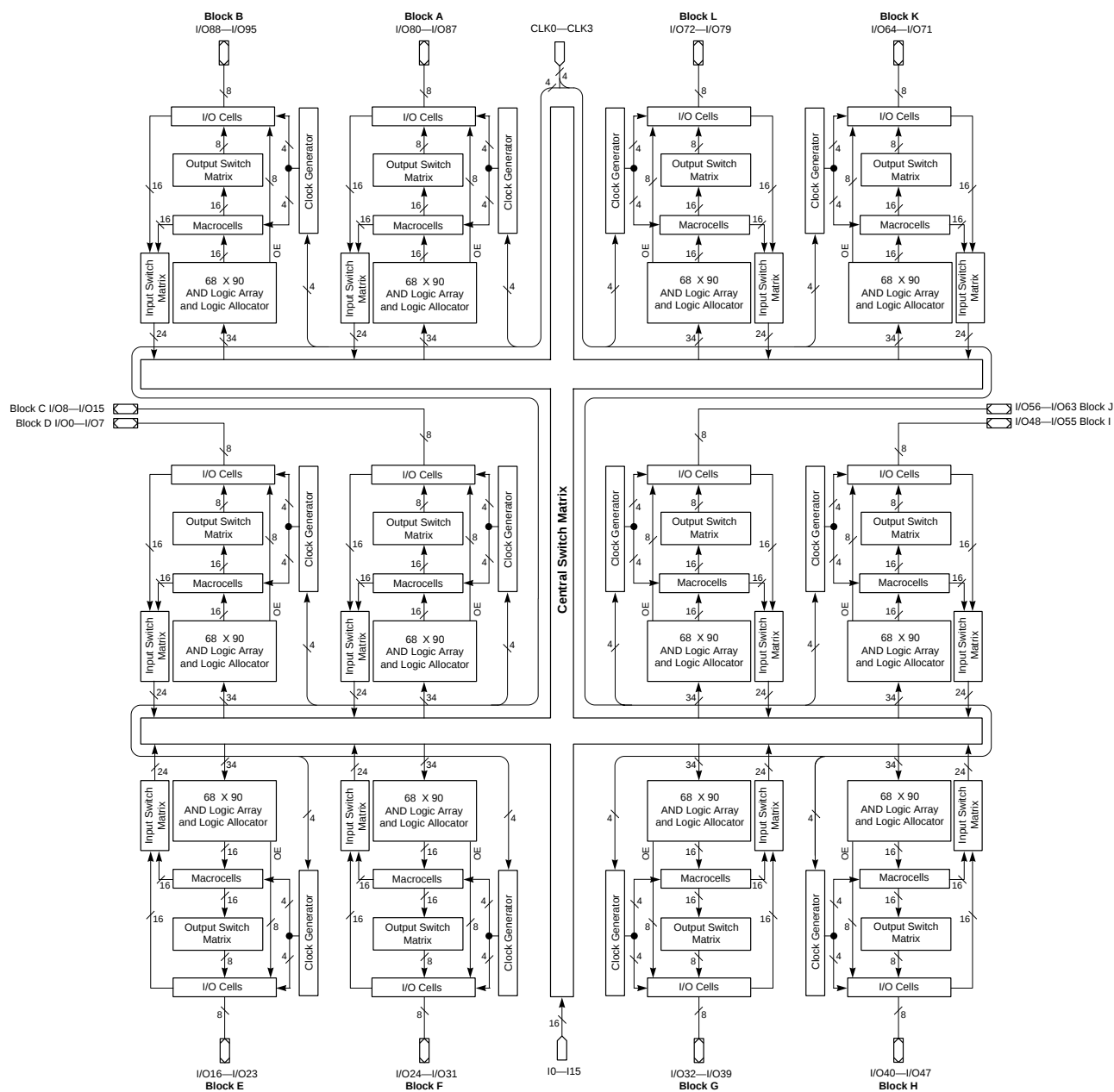
ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

BLOCK DIAGRAM – M4A(3,5)-64/32



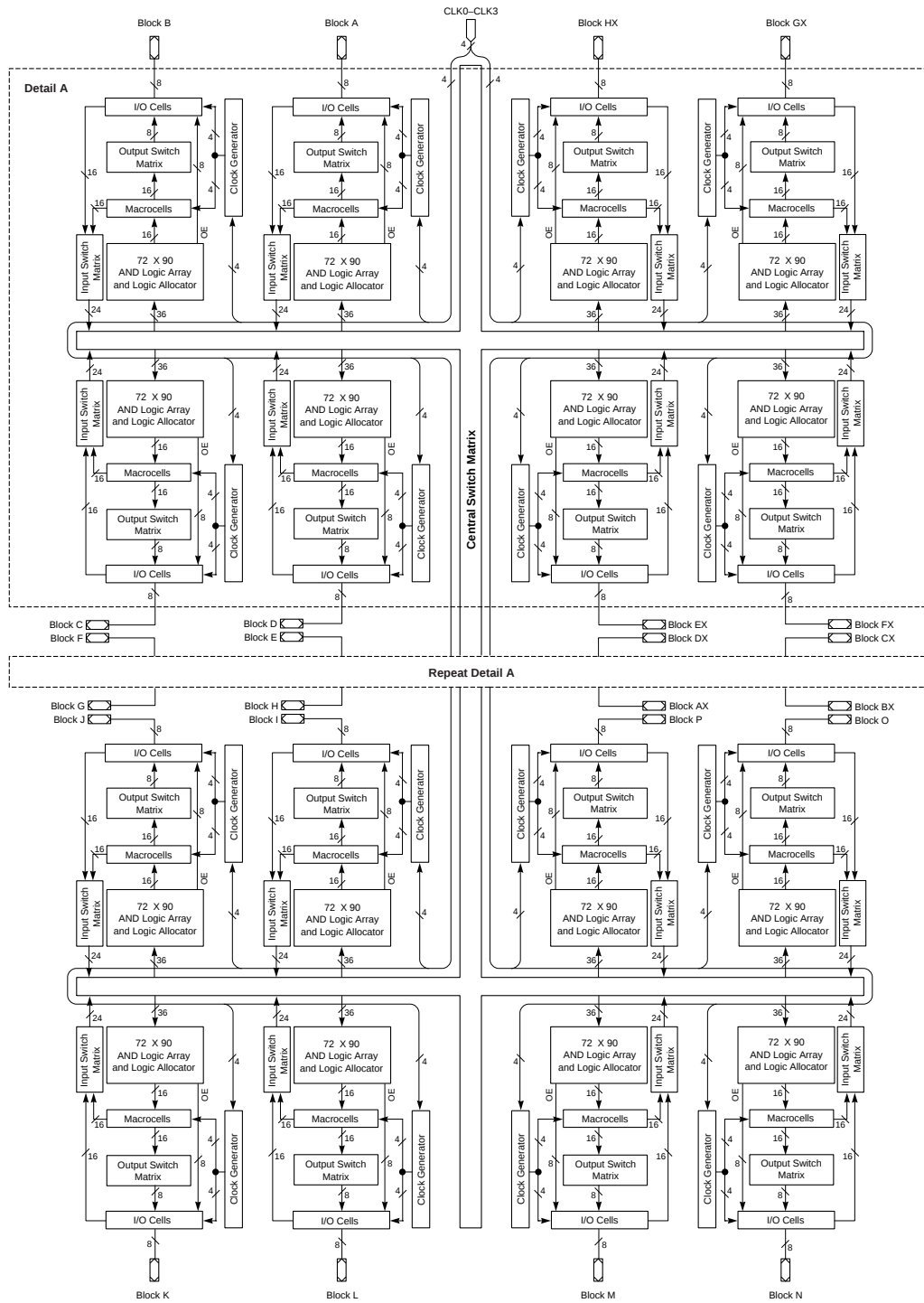
17466H-020

BLOCK DIAGRAM – M4A(3,5)-192/96



17466G-067

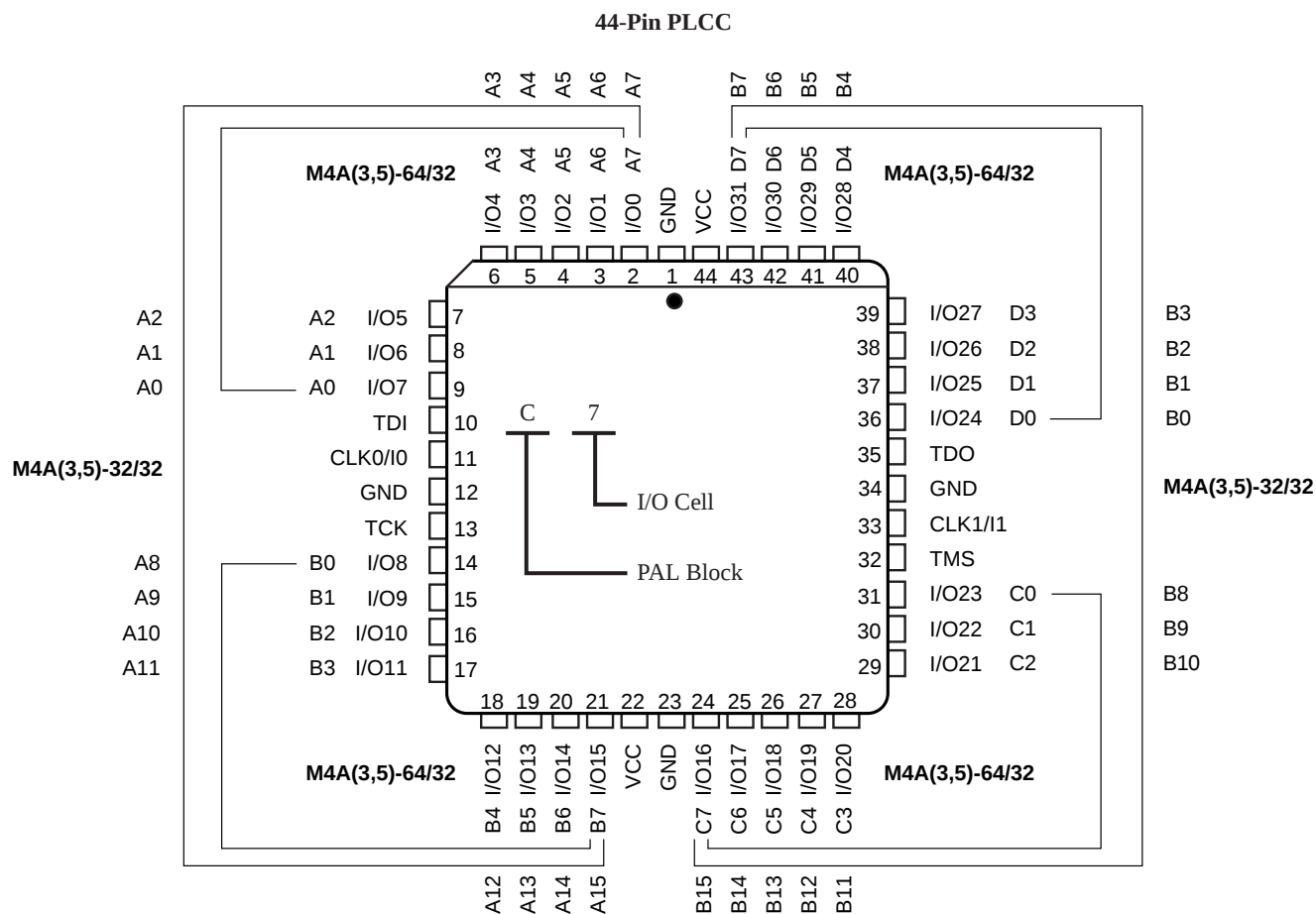
BLOCK DIAGRAM – M4A3-384/160, M4A3-384/192



17466G-067

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

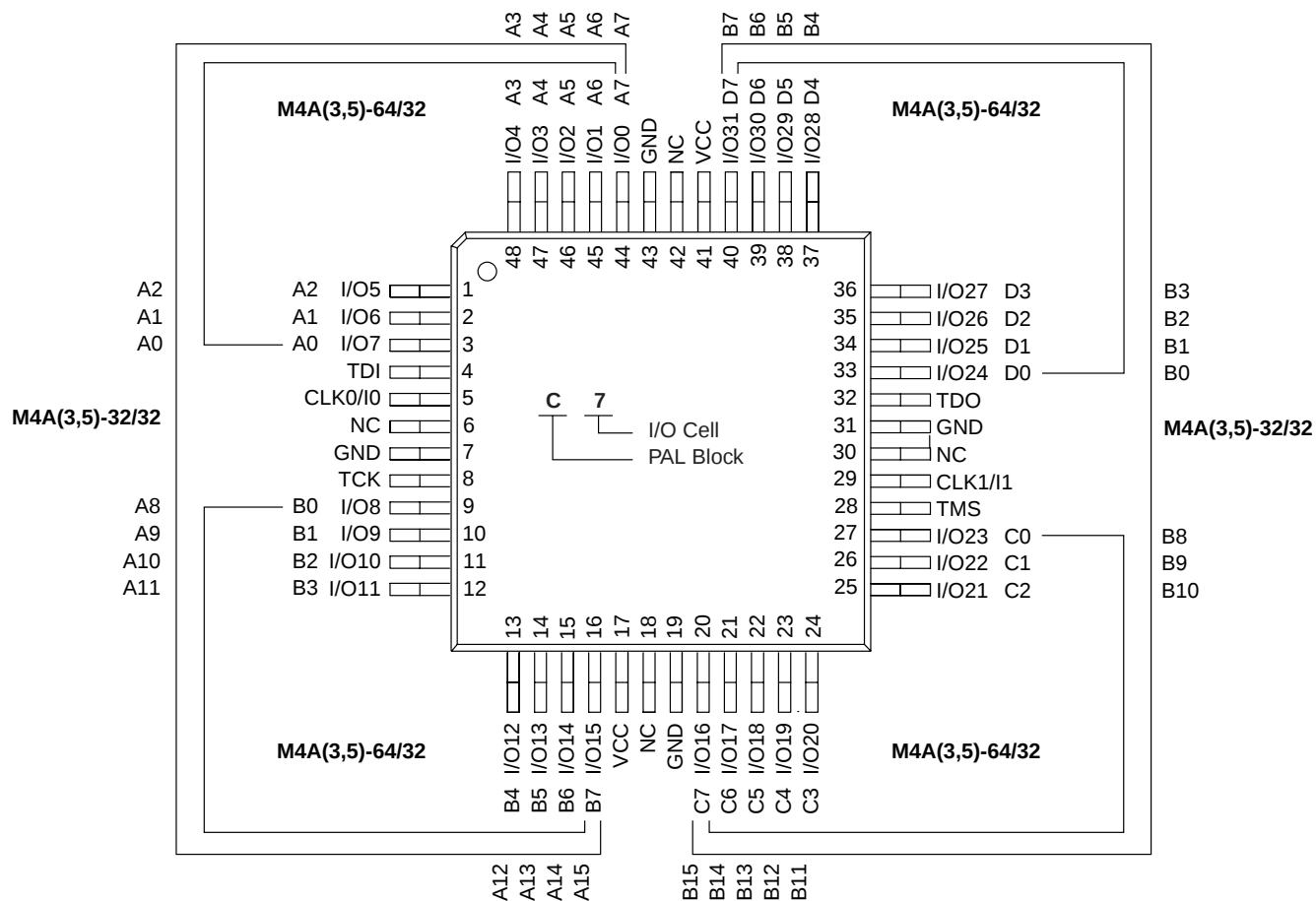
TMS = Test Mode Select

TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

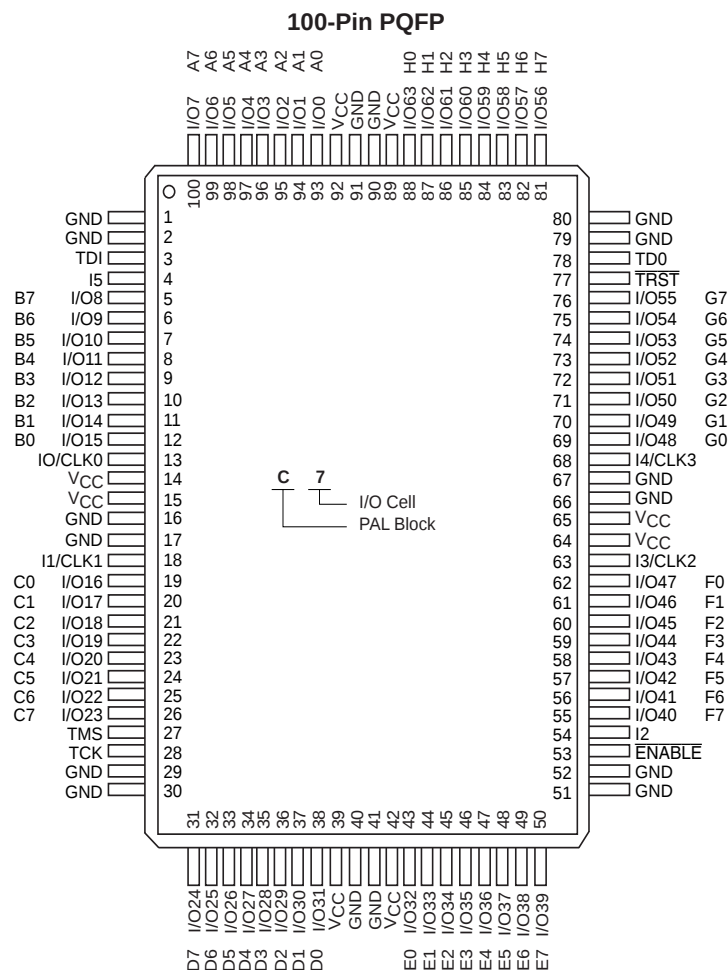
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

Top View



17466G-031

PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

100-BALL caBGA CONNECTION DIAGRAM (M4A3-128/64)

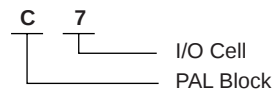
Bottom View

100-Ball caBGA

	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O63 H7	I/O60 H4	I/O57 H1	GND	GND	I/O1 A1	I/O4 A4	I/O7 A7	GND	A
B	TRST	GND	I/O61 H5	I5	VCC	I/O0 A0	I/O6 A6	GND	TDI	I/O15 B7	B
C	I/O53 G5	TDO	I/O62 H6	I/O58 H2	I/O56 H0	I/O2 A2	GND	I/O14 B6	I/O13 B5	I/O12 B4	C
D	I/O50 G2	I/O55 G7	GND	I/O59 H3	I/O3 A3	I/O5 A5	I/O11 B3	I/O10 B2	CLK0/I0	I/O9 B1	D
E	CLK3/I4	I/O49 G1	I/O51 G3	I/O54 G6	VCC	I/O16 C0	I/O20 C4	I/O8 B0	VCC	GND	E
F	GND	VCC	I/O40 F0	I/O52 G4	I/O48 G0	VCC	I/O22 C6	I/O19 C3	I/O17 C1	CLK1/I1	F
G	I/O41 F1	CLK2/I3	I/O42 F2	I/O43 F3	I/O37 E5	I/O35 E3	I/O27 D3	GND	I/O23 C7	I/O18 C2	G
H	I/O44 F4	I/O45 F5	I/O46 F6	GND	I/O34 E2	I/O24 D0	I/O26 D2	I/O30 D6	TCK	I/O21 C5	H
J	I/O47 F7	ENABLE	GND	I/O38 E6	I/O32 E0	VCC	I2	I/O29 D5	GND	TMS	J
K	GND	I/O39 E7	I/O36 E4	I/O33 E1	GND	GND	I/O25 D1	I/O28 D4	I/O31 D7	GND	K
	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out
 TRST = Test Reset
 ENABLE = Program



17466G-100cabga

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-384/192)

Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O175 FX7	I/O181 GX5	I/O180 GX4	I/O177 GX1	I/O166 EX6	I/O164 EX4	I/O191 HX7	I/O186 HX2	I/O1 A1	I/O3 A3	CLK0	I/O25 D1	I/O29 D5	I/O31 D7	I/O10 B2	I/O12 B4	A
B	I/O173 FX5	I/O174 FX6	I/O182 GX6	I/O179 GX3	I/O167 EX7	I/O165 EX5	I/O160 EX0	I/O187 HX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O26 D2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O171 FX3	I/O172 FX4	N/C	I/O183 GX7	I/O178 GX2	I/O162 EX2	I/O163 EX3	I/O189 HX5	I/O184 HX0	I/O6 A6	I/O28 D4	I/O30 D6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	I/O150 CX6	I/O151 CX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O148 CX4	N/C	I/O170 FX2	VCC	I/O168 FX0	169 FX1	I/O190 HX6	CLK3	I/O188 HX4	I/O2 A2	I/O24 D0	N/C	GND	I/O20 C4	I/O19 C3	I/O47 F7	E
F	I/O144 CX0	I/O149 CX5	I/O147 CX3	GND	I/O146 CX2	I/O145 CX1	I/O176 GX0	I/O161 EX1	I/O185 HX1	I/O4 A4	I/O27 D3	I/O18 C2	VCC	I/O16 C0	I/O46 F6	I/O45 F5	F
G	I/O155 DX3	I/O158 DX6	I/O157 DX5	VCC	I/O156 DX4	I/O159 DX7	VCC	GND	GND	VCC	I/O17 C1	I/O44 F4	GND	I/O42 F2	I/O41 F1	I/O39 E7	G
H	I/O152 DX0	I/O154 DX2	I/O153 DX1	GND	I/O128 AX0	I/O129 AX1	GND	VCC	VCC	GND	I/O43 F3	I/O40 F0	VCC	I/O36 E4	I/O35 E3	I/O34 E2	H
J	I/O130 AX2	I/O131 AX3	I/O132 AX4	GND	I/O134 AX6	I/O133 AX5	GND	VCC	VCC	GND	I/O38 E6	I/O37 E5	GND	I/O57 H1	I/O56 H0	I/O58 H2	J
K	I/O135 AX7	I/O136 BX0	I/O137 BX1	VCC	I/O139 BX3	I/O138 BX2	VCC	GND	GND	VCC	I/O33 E1	I/O32 E0	VCC	I/O63 H7	I/O62 H6	I/O48 G0	K
L	I/O140 BX4	I/O141 BX5	I/O143 BX7	GND	I/O114 O2	I/O142 BX6	I/O98 M2	I/O91 L3	I/O67 I3	I/O69 I5	I/O60 H4	I/O59 H3	GND	I/O51 G3	I/O52 G4	I/O49 G1	L
M	I/O112 O0	I/O113 O1	I/O115 O3	GND	I/O123 P3	I/O121 P1	I/O100 M4	I/O90 L2	I/O66 I2	I/O80 K0	I/O83 K3	I/O61 H5	VCC	I/O76 J4	I/O55 G7	I/O50 G2	M
N	I/O116 O4	I/O117 O5	I/O119 O7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O72 J0	I/O53 G5	N
P	I/O118 O6	I/O109 N5	I/O110 N6	I/O111 N7	I/O124 P4	I/O122 P2	I/O101 M5	I/O89 L1	I/O93 L5	I/O94 L6	I/O71 I7	I/O84 K4	I/O87 K7	TMS	I/O73 J1	I/O54 G6	P
R	I/O108 N4	I/O107 N3	I/O104 N0	I/O127 P7	I/O120 P0	I/O102 M6	I/O99 M3	I/O96 M0	I/O92 L4	I/O64 I0	I/O68 I4	I/O81 K1	I/O85 K5	I/O79 J7	I/O75 J3	I/O74 J2	R
T	I/O106 N2	I/O105 N1	I/O126 P6	I/O125 P5	I/O103 M7	CLK2	I/O97 M1	I/O88 L0	CLK1	I/O95 L7	I/O65 I1	I/O70 I6	I/O82 K2	I/O86 K6	I/O78 J6	I/O77 J5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 N/C = No Connect
 VCC = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



m4a3.384.192_256bga

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/192)

Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O159 KX7	I/O181 OX5	I/O180 OX4	I/O177 OX1	I/O174 NX6	I/O172 NX4	I/O191 PX7	I/O186 PX2	I/O1 A1	I/O3 A3	CLK0	I/O17 C1	I/O21 C5	I/O23 C7	I/O10 B2	I/O12 B4	A
B	I/O157 KX5	I/O158 KX6	I/O182 OX6	I/O179 OX3	I/O175 NX7	I/O173 NX5	I/O168 NX0	I/O187 PX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O18 C2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	B
C	I/O155 KX3	I/O156 KX4	N/C	I/O183 OX7	I/O178 OX2	I/O170 NX2	I/O171 NX3	I/O189 PX5	I/O184 PX0	I/O6 A6	I/O20 C4	I/O22 C6	I/O15 B7	I/O14 B6	TDI	I/O39 F7	C
D	I/O150 JX6	I/O151 JX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O38 F6	I/O37 F5	D
E	I/O148 JX4	N/C	I/O154 KX2	VCC	I/O152 KX0	I/O153 KX1	I/O190 PX6	CLK3	I/O188 PX4	I/O2 A2	I/O16 C0	N/C	GND	I/O36 F4	I/O35 F3	I/O47 G7	E
F	I/O144 JX0	I/O149 JX5	I/O147 JX3	GND	I/O146 JX2	I/O145 JX1	I/O176 OX0	I/O169 NX1	I/O185 PX1	I/O4 A4	I/O19 C3	I/O34 F2	VCC	I/O32 F0	I/O46 G6	I/O45 G5	F
G	I/O163 LX3	I/O166 LX6	I/O165 LX5	VCC	I/O164 LX4	I/O167 LX7	VCC	GND	GND	VCC	I/O33 F1	I/O44 G4	GND	I/O42 G2	I/O41 G1	I/O31 E7	G
H	I/O160 LX0	I/O162 LX2	I/O161 LX1	GND	I/O120 EX0	I/O121 EX1	GND	VCC	VCC	GND	I/O43 G3	I/O40 G0	VCC	I/O28 E4	I/O27 E3	I/O26 E2	H
J	I/O122 EX2	I/O123 EX3	I/O124 EX4	GND	I/O126 EX6	I/O125 EX5	GND	VCC	VCC	GND	I/O30 E6	I/O29 E5	GND	I/O65 L1	I/O64 L0	I/O66 L2	J
K	I/O127 EX7	I/O136 GX0	I/O137 GX1	VCC	I/O139 GX3	I/O138 GX2	VCC	GND	GND	VCC	I/O25 E1	I/O24 E0	VCC	I/O71 L7	I/O70 L6	I/O48 J0	K
L	I/O140 GX4	I/O141 GX5	I/O143 GX7	GND	I/O130 FX2	I/O142 GX6	I/O98 AX2	I/O91 P3	I/O75 N3	I/O77 N5	I/O68 L4	I/O67 L3	GND	I/O51 J3	I/O52 J4	I/O49 J1	L
M	I/O128 FX0	I/O129 FX1	I/O131 FX3	GND	I/O115 CX3	I/O113 CX1	I/O100 AX4	I/O90 P2	I/O74 N2	I/O80 O0	I/O83 O3	I/O69 L5	VCC	I/O60 K4	I/O55 J7	I/O50 J2	M
N	I/O132 FX4	I/O133 FX5	I/O135 FX7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O56 K0	I/O53 J5	N
P	I/O134 FX6	I/O109 BX5	I/O110 BX6	I/O111 BX7	I/O116 CX4	I/O114 CX2	I/O101 AX5	I/O89 P1	I/O93 P5	I/O94 P6	I/O79 N7	I/O84 O4	I/O87 O7	TMS	I/O57 K1	I/O54 J6	P
R	I/O108 BX4	I/O107 BX3	I/O104 BX0	I/O119 CX7	I/O112 CX0	I/O102 AX6	I/O99 AX3	I/O96 AX0	I/O92 P4	I/O72 N0	I/O76 N4	I/O81 O1	I/O85 O5	I/O63 K7	I/O59 K3	I/O58 K2	R
T	I/O106 BX2	I/O105 BX1	I/O118 CX6	I/O117 CX5	I/O103 AX7	CLK2	I/O97 AX1	I/O88 P0	CLK1	I/O95 P7	I/O73 N1	I/O78 N6	I/O82 O2	I/O86 O6	I/O62 K6	I/O61 K5	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

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m4a3.512.192_256bga

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10,	JC, VC, VC48
M4A5-64/32	-55, -7, -10	JC, VC, VC48
M4A5-96/48		VC
M4A5-128/64		YC, VC
M4A5-192/96	-6, -7, -10	VC
M4A5-256/128	-65, -7, -10	YC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	JJ, VI, VI48
M4A5-64/32	-7, -10, -12	JJ, VI, VI48
M4A5-96/48		VI
M4A5-128/64		YI, VI
M4A5-192/96	-7, -10, -12	VI
M4A5-256/128	-10, -12	YI

Lead-free Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A3-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A3-64/64		VNC
M4A3-128/64		VNC
M4A3-192/96	-6, -7, -10	VNC
M4A3-256/128	-55, -7, -10	FANC, YNC
M4A3-256/160	-7, -10	YNC
M4A3-256/192		FANC
M4A3-384/192	-65, -10, -12	FANC
M4A3-512/192	-7, -10, -12	FANC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A3-64/32		VNI, VNI48, JNI
M4A3-64/64		VNI
M4A3-128/64		VNI
M4A3-192/96	-10, -12	VNI
M4A3-256/128		FANI, YNI
M4A3-256/160		YNI
M4A3-256/192	-10, -12, -14	FANI
M4A3-384/192		FANI
M4A3-512/192		FANI

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A5-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A5-96/48		VNC
M4A5-128/64		VNC, YNC
M4A5-192/96	-6, -7, -10	VNC
M4A5-256/128	-65, -7, -10	YNC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A5-64/32		VNI, VNI48, JNI
M4A5-96/48		VNI
M4A5-128/64		VNI, YNI
M4A5-192/96		VNI
M4A5-256/128		YNI

Most ispMACH devices are dual-marked with both Commercial and Industrial grades. The Industrial speed grade is slower, i.e., M4A3-256/128-7YC-10YI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.